



Creative
Interconnect
Solutions

Matr'YX



→ **High-density** BGA
board-to-board
connectors

HARSH ENVIRONMENT APPLICATIONS



Never worry about connector height again



High speed – High density



Defense



Aeronautics



Space

...and much more

→ High vibration

→ Thermal Vacuum Outgassing ECSS compliant

→ Reliability

→ Modularity

→ Space saving

→ High altitude

→ Shock resistance

→ Weight saving

Maximum robustness through improved shock and vibration

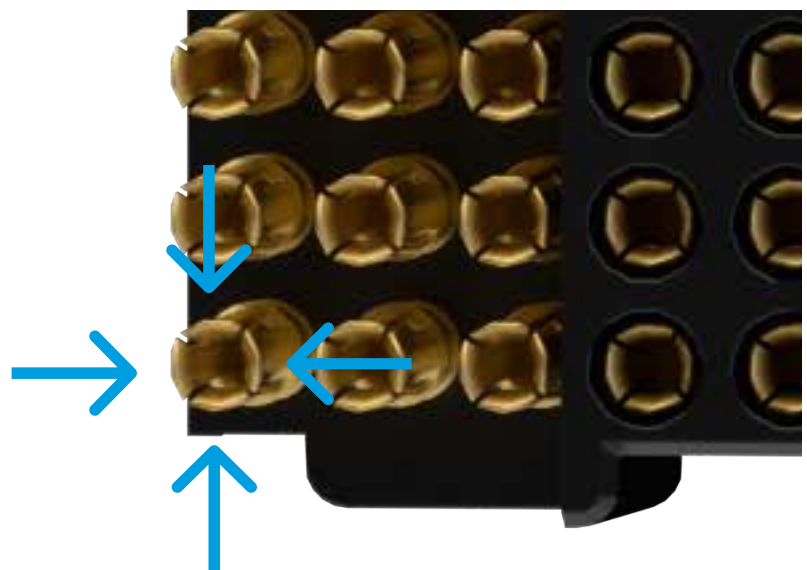
Contacts with 4 points of contacts: a unique feature for a 1mm pitch connector

Reducing fretting corrosion

Through gold layer optimization

Long term reliability

Specifically designed to allow underfill application, improving mechanical strength and extending the lifespan of PCB assemblies



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Product specifications

MATERIAL

Insulator: High Temp. Liquid Crystal Polymer (LCP)

Contact: copper alloy

Plating: Ni 1.27μ + Au 0.8μ mini (options: Au 1.27μ mini)

Lead free solder ball Ø600μ: 96.55n/3.0Ag/0.5Cu (SAC305)

ENVIRONMENTAL

Vibration: 30 gRMS / 5 to 2000Hz (0.46 g2/hz)

Temperature cycling: -55°C/ +125°C

Rapid temperature variation: 1000 cycles -40°C / +100° C (10°C / min)

Humidity resistance 10 cycles 24h 65°C / >95% RH

Salt spray: 48h

ELECTRICAL

Withstanding voltage: 600 Vrms

Withstanding voltage at 50 000 ft: 100 Vrms

Currently capacity 1A at 25°C 0.5A at 85°C

Contact resistance 10m Ω max. (at 1A)

Insulation resistance 1GΩ min.

MECHANICAL

Connector mating/unmating force: 100N maxi for 301 contacts

Durability: 100 cycles

OTHER

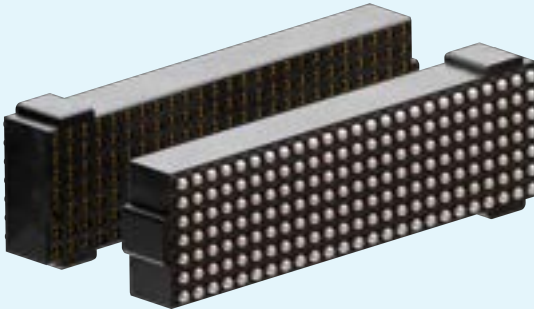
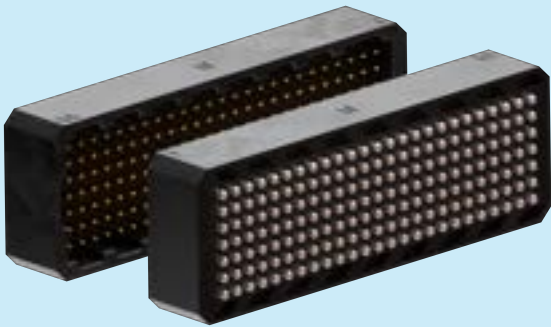
Underfill process compatibility

Part numbering

MALE CONNECTOR:
MYX1-Hx-nnn-Gy.yy



FEMALE CONNECTOR:
MYX2-Hx-nnn-Gy.yy



→ Hx
connector height
H1/H2/H3/H4/H5

→ nnn
number of contacts

→ Gy.yy
gold plating thickness, G0.8
or G1.27